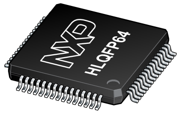

SOT1510-2

HLQFP64, plastic, thermal enhanced low profile quad flat package; 64 terminals; 0.5 mm pitch; 10 mm x 10 mm x 1.4 mm body

24 July 2018 Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP64
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026 BCD
Mounting method type	S (surface mount)
Issue date	24-07-2018
Manufacturer package code	98ASA10763D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	10	-	mm
package width	-	10	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	

2 Package outline

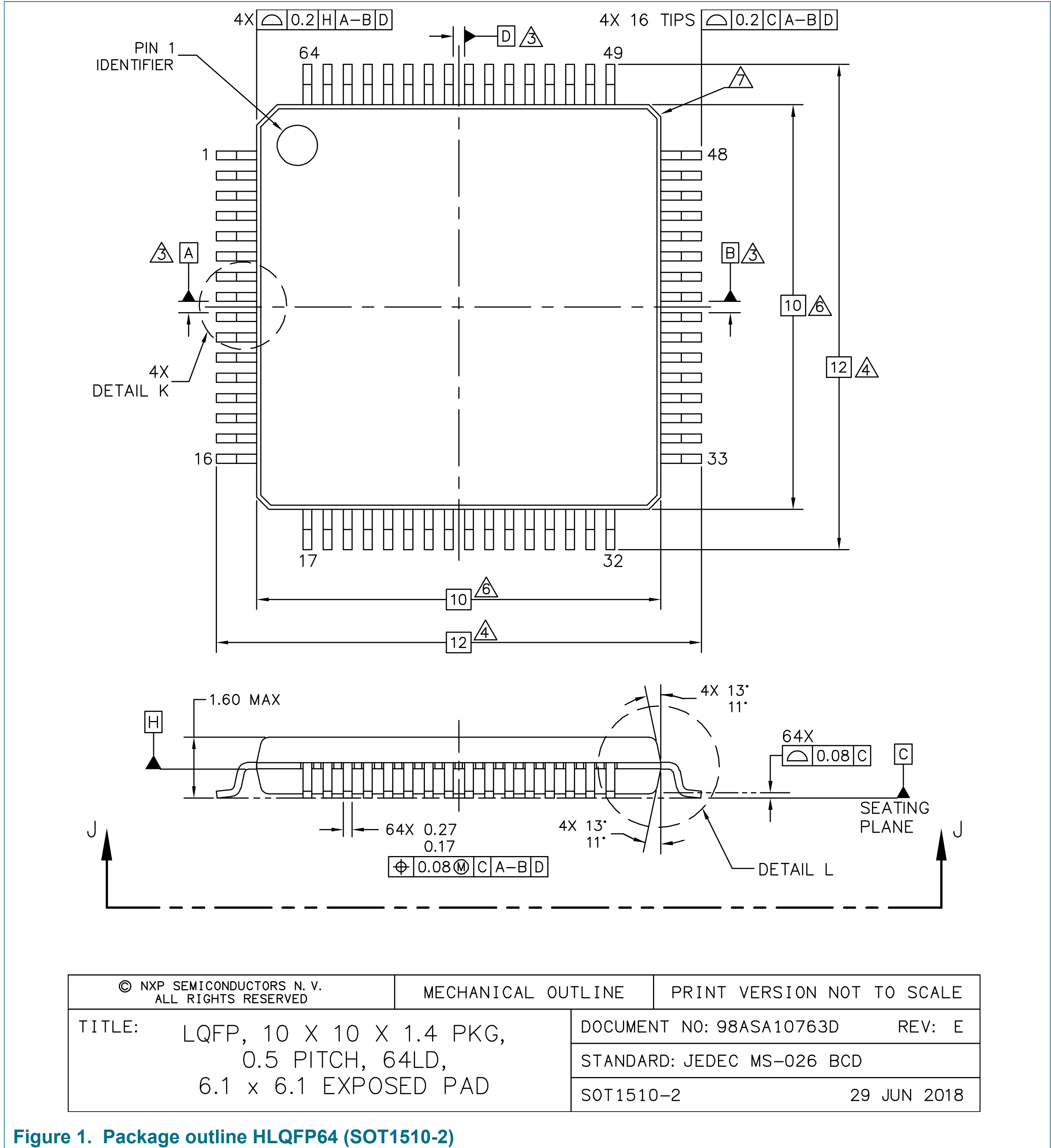

Figure 1. Package outline HLQFP64 (SOT1510-2)

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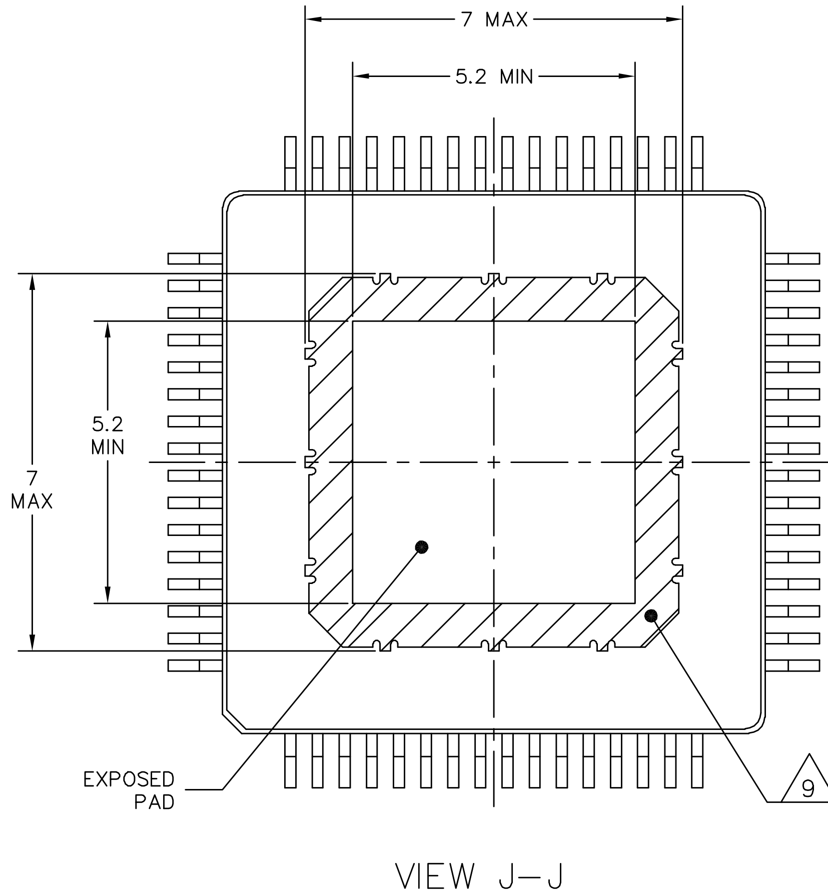

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TITLE: LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, 64LD, 6.1 x 6.1 EXPOSED PAD	DOCUMENT NO: 98ASA10763D	REV: E
	STANDARD: JEDEC MS–026 BCD	
	SOT1510–2	29 JUN 2018

Figure 2. Package outline dt1 HLQFP64 (SOT1510-2)

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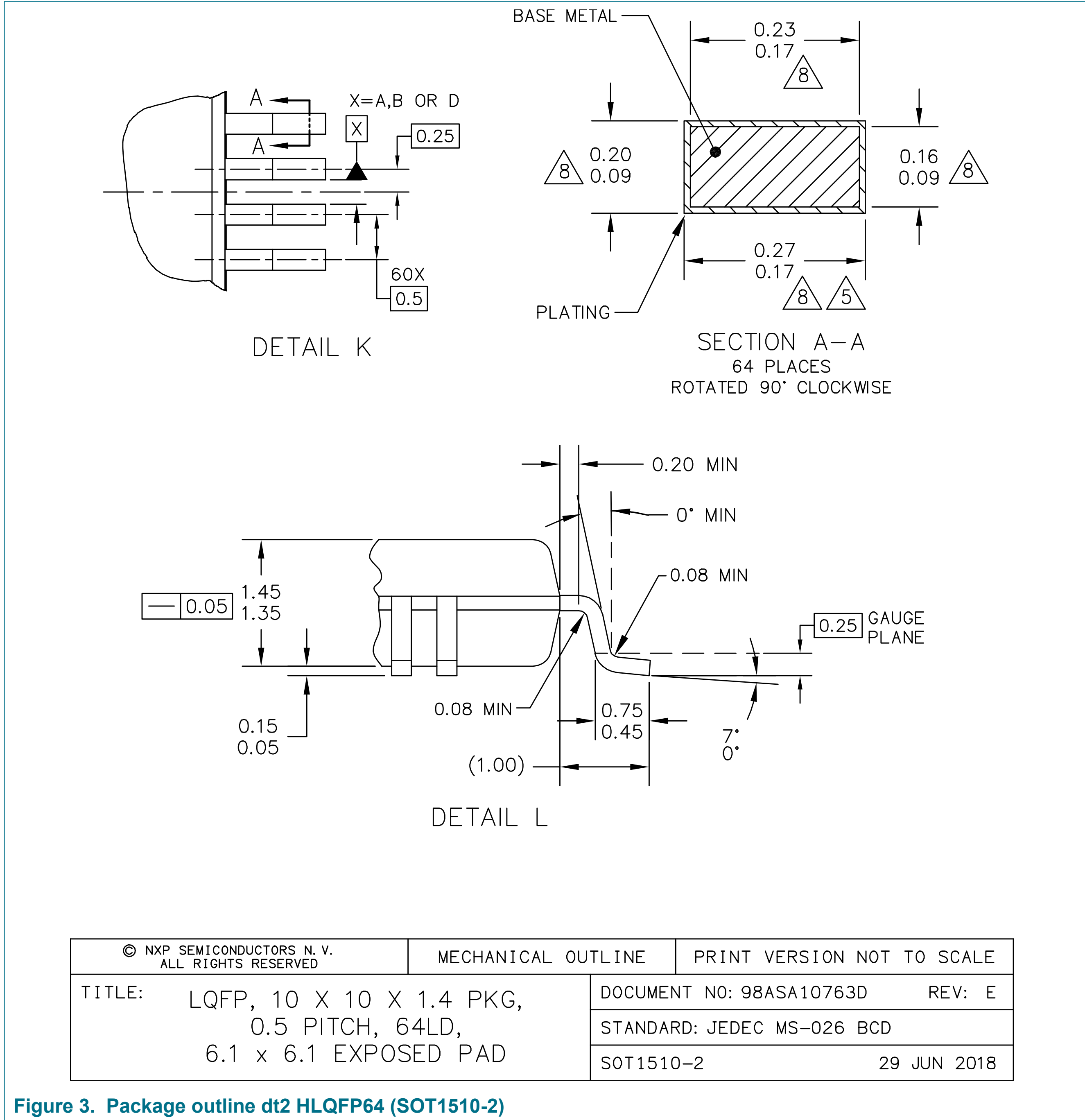

Figure 3. Package outline dt2 HLQFP64 (SOT1510-2)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.

9. HATCHED AREA REPRESENTS POSSIBLE MOLD FLASH ON EXPOSED PAD.

10. KEEP OUT ZONE REPRESENTS AREA ON PCB THAT MUST NOT HAVE ANY EXPOSED METAL (EG. TRACE/VIA) FOR PCB ROUTING DUE TO THE POSSIBILITY OF SHORTING TO TIE BAR/EXPOSED PAD.

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TITLE: LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, 64LD, 6.1 x 6.1 EXPOSED PAD	DOCUMENT NO: 98ASA10763D	REV: E
	STANDARD: JEDEC MS-026 BCD	
	SOT1510-2	29 JUN 2018

Figure 4. Package outline note HLQFP64 (SOT1510-2)

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3 Soldering

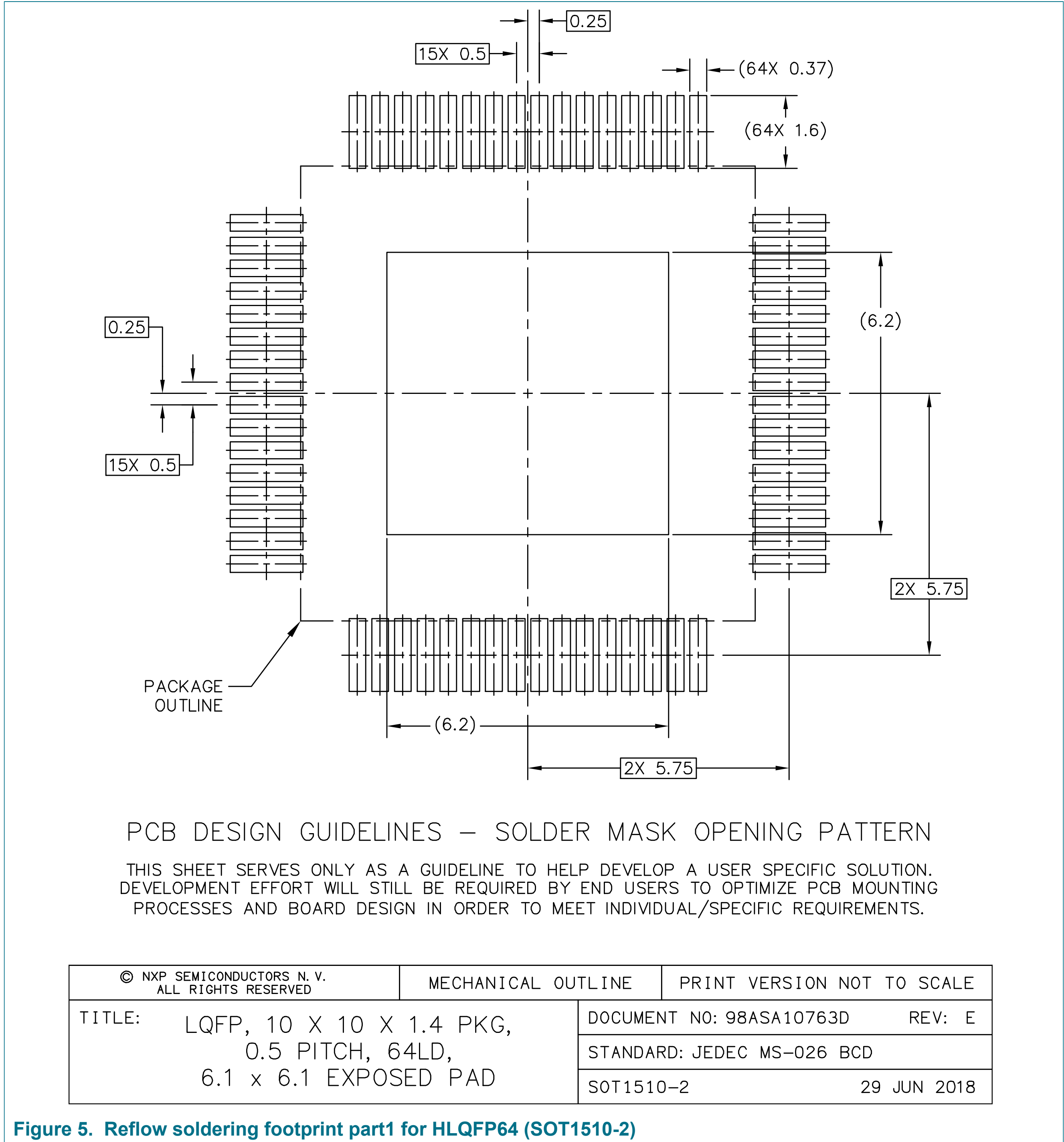

Figure 5. Reflow soldering footprint part1 for HLQFP64 (SOT1510-2)

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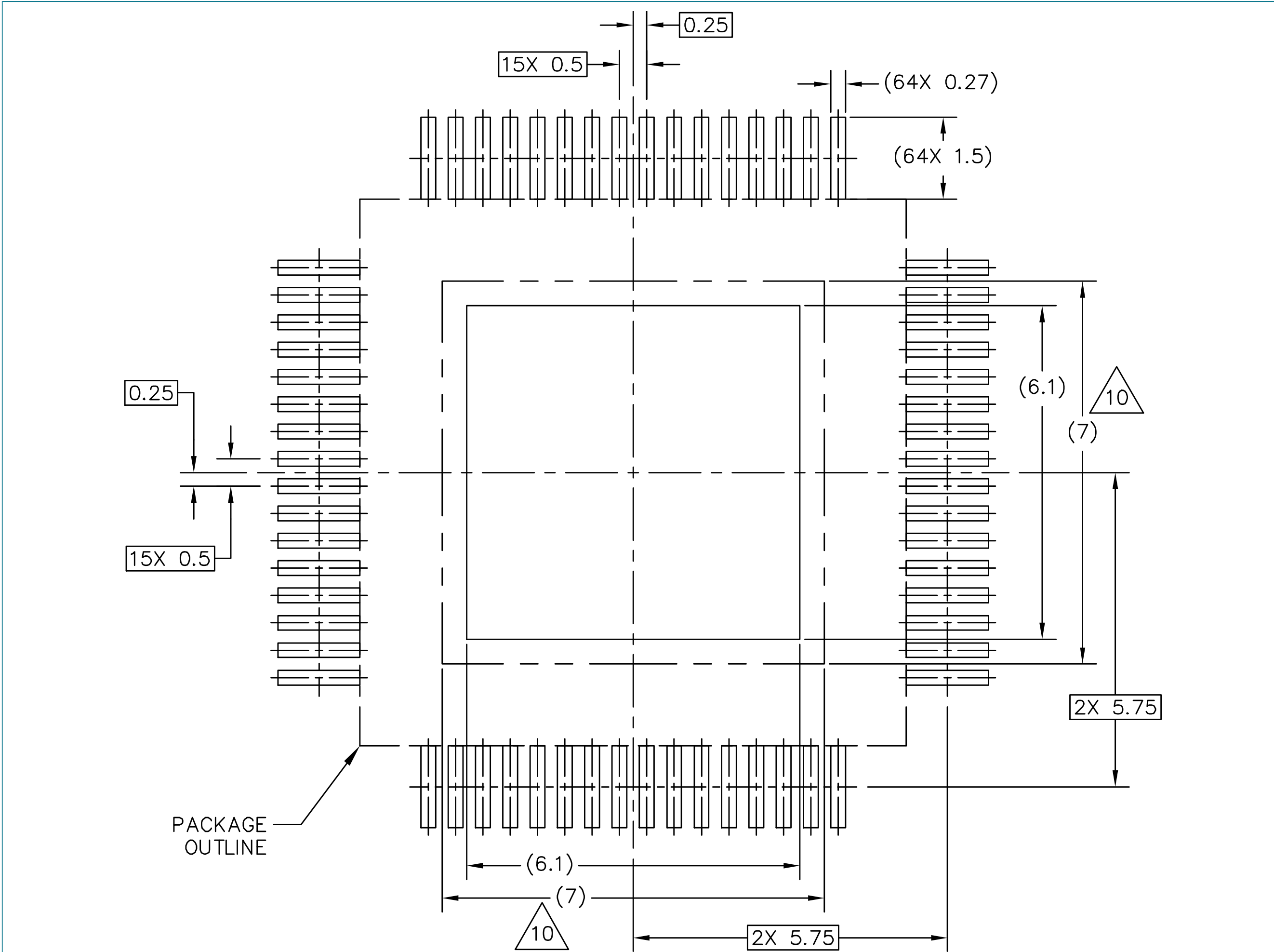

PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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TITLE: LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, 64LD, 6.1 x 6.1 EXPOSED PAD	DOCUMENT NO: 98ASA10763D	REV: E
	STANDARD: JEDEC MS-026 BCD	
	SOT1510-2	29 JUN 2018

Figure 6. Reflow soldering footprint part2 for HLQFP64 (SOT1510-2)

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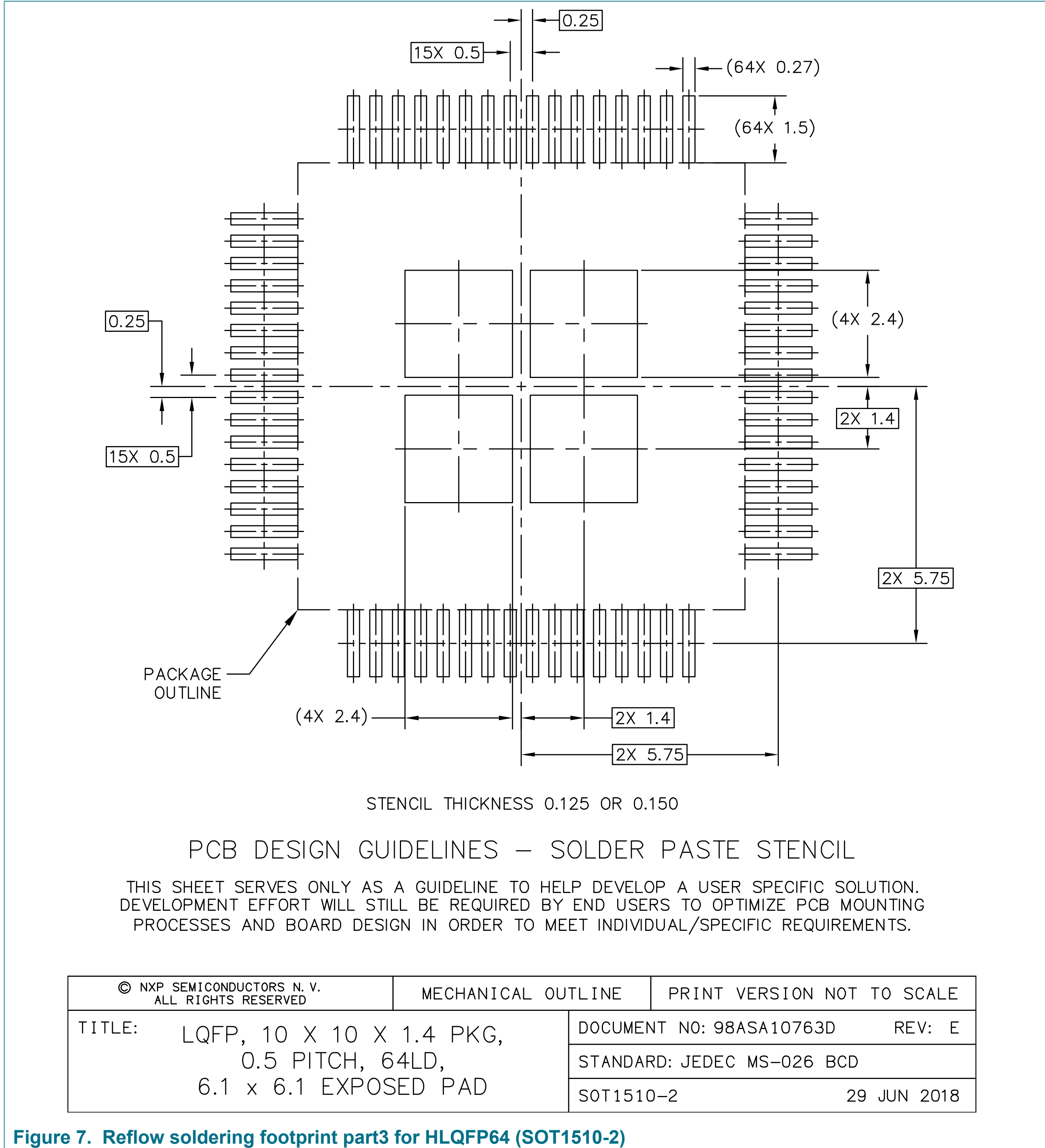

Figure 7. Reflow soldering footprint part3 for HLQFP64 (SOT1510-2)

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4 Legal information

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